





#### 100V PNP MEDIUM POWER TRANSISTOR IN SOT89

#### **Features**

- BV<sub>CEO</sub> > -100V
- BV<sub>ECO</sub> > -7V
- I<sub>C</sub> = -2A High Continuous Collector Current
- I<sub>CM</sub> = -3A Peak Collector Current
- V<sub>CE(SAT)</sub> < 130mV @ -1A</li>
- R<sub>CE(SAT)</sub> = 100mΩ for a Low Equivalent On-Resistance
- Complementary NPN Type: ZXTN19100CZ
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

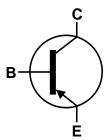
#### **Mechanical Data**

- Case: SOT89
- Case Material: Molded Plastic. "Green" Molding Compound UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208(3)
- Weight: 0.05 grams (Approximate)

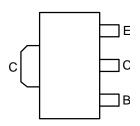




Top View



Device Symbol



Top View Pin Out

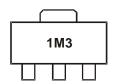
#### Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
ZXTP19100CZTA	AEC-Q101	1M3	7	12	1,000
ZXTP19100CZQTA	Automotive	1M3	7	12	1,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_compliance\_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



1M3 = Product Type Marking Code



### Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Limit	Unit
Collector-Base Voltage	$V_{CBO}$	-110	V
Collector-Emitter Voltage (Forward Blocking)	V <sub>CEX</sub>	-110	V
Collector-Emitter Voltage	$V_{\sf CEO}$	-100	V
Emitter-Collector Voltage (Reverse Blocking)	V <sub>ECO</sub>	-7	V
Emitter-Base Voltage	$V_{EBO}$	-7	V
Continuous Collector Current	Ic	-2	А
Peak Pulse Current	I <sub>CM</sub>	-3	Α
Base Current	I <sub>B</sub>	-1	Α

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
	(Note 6)		1.1 8.8	1	
Power Dissipation	(Note 7)	P <sub>D</sub>	1.8 14.4	W mW/°C	
Linear Derating Factor	(Note 8)		2.4 19.2		
	(Note 9)		4.46 35.7		
	(Note 6)		117		
Thermal Resistance, Junction to Ambient Air	(Note 7)	<b>D</b>	68	°C/W	
Thermal Resistance, Junction to Ambient Air	(Note 8)	$R_{ heta JA}$	51		
	(Note 9)		28		
Thermal Resistance, Junction to Lead	(Note 10)	$R_{ heta JL}$	4.7		
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +150	°C		

### ESD Ratings (Note 11)

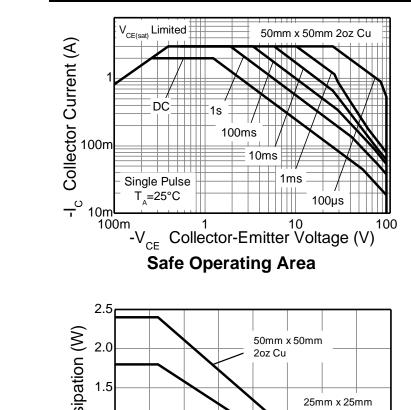
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

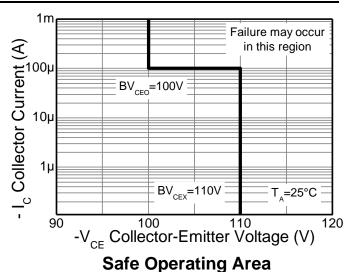
Notes:

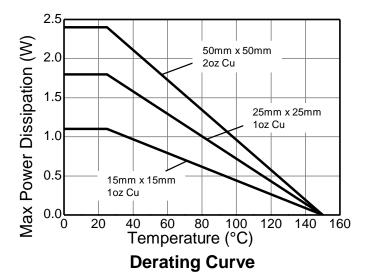
- 6. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 0.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 7. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
- 8. Same as Note 6, except the device is mounted on 50mm x 50mm 2oz copper.9. Same as Note 8, except the device is measured at t<5 seconds.</li>
- Same as Note 6, except the device is measured at 1<3 seconds.</li>
   Thermal resistance from junction to solder-point (on the exposed collector pad).
- 11. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



## **Thermal Characteristics and Derating Information**

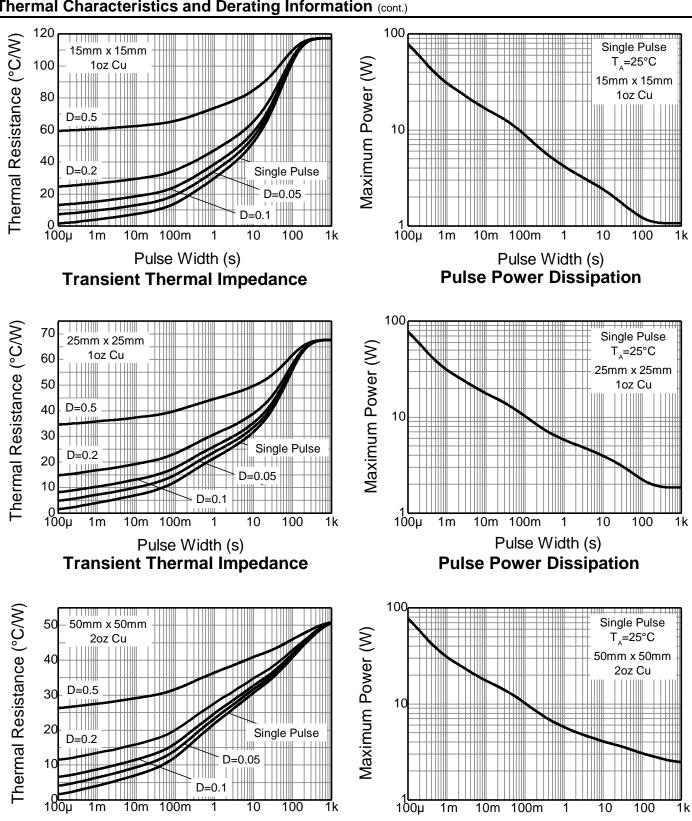








## Thermal Characteristics and Derating Information (cont.)



Pulse Width (s)

Transient Thermal Impedance

Pulse Width (s)

**Pulse Power Dissipation** 



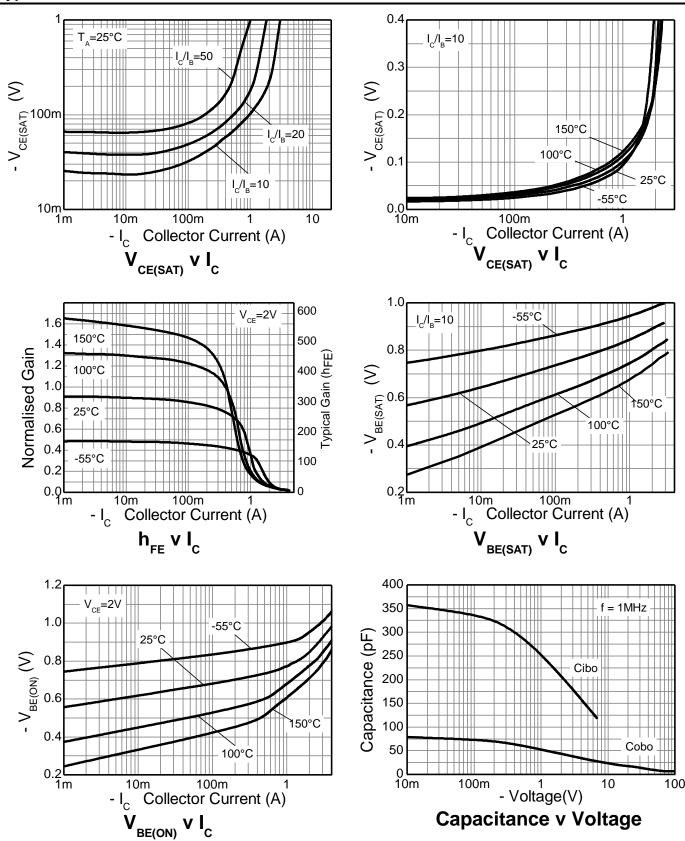
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-110	-135	_	V	$I_C = -100 \mu A$
Collector-Emitter Breakdown Voltage	BV <sub>CEX</sub>	-110	-135	_	V	$I_E = -100\mu A$ , $R_{BC} < 1k\Omega$ or 0.25V > $V_{BC} > -0.25V$
Collector-Emitter Breakdown Voltage (Note 12)	BV <sub>CEO</sub>	-100	-135	_	V	I <sub>C</sub> = -10mA
Emitter-Collector Breakdown Voltage (Reverse Blocking)	BV <sub>ECX</sub>	-7	-8.3	_	V	$I_E$ = -100μA, $R_{BC}$ <1k $\Omega$ or 0.25V > $V_{BC}$ > -0.25V
Emitter-Collector Breakdown Voltage (Reverse Blocking)	BV <sub>ECO</sub>	-7	-8.7	_	V	I <sub>E</sub> = -100μA
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-7	-8.3	_	V	$I_E = -100 \mu A$
Collector-Base Cutoff Current	I <sub>CBO</sub>	1	<1	-50 -0.5	nΑ μΑ	V <sub>CB</sub> = -110V V <sub>CB</sub> = -110V, T <sub>A</sub> = +100°C
Emitter Cutoff Current	I <sub>EBO</sub>	_	<1	-50	nA	$V_{EB} = -5.6V$
DC Current Transfer Static Ratio (Note 12)	h <sub>FE</sub>	200 70 20	300 130 25	500 — —	_	I <sub>C</sub> = -100mA, V <sub>CE</sub> = -2V I <sub>C</sub> = -1A, V <sub>CE</sub> = -2V I <sub>C</sub> = -2A, V <sub>CE</sub> = -2V
Collector-Emitter Saturation Voltage (Note 12)	$V_{\text{CE(sat)}}$	-	-100 -100 -180 -220	-130 -125 -230 -295	mV	$I_C = -0.5\text{mA}, I_B = -20\text{mA}$ $I_C = -1\text{A}, I_B = -100\text{mA}$ $I_C = -1\text{A}, I_B = -50\text{mA}$ $I_C = -2\text{A}, I_B = -200\text{mA}$
Base-Emitter Saturation Voltage (Note 12)	V <sub>BE(sat)</sub>	_	-890	-1000	mV	$I_C = -2A$ , $I_B = -200mA$
Base-Emitter Turn-on Voltage (Note 12)	V <sub>BE(on)</sub>	_	-840	-950	mV	I <sub>C</sub> = -2A, V <sub>CE</sub> = -2V
Transitional Frequency	$f_{T}$	_	142	_	MHz	$I_E = -100 \text{mA}, V_{CE} = -10 \text{V}$ f = 50 MHz
Input Capacitance	Cibo	_	291	400	pF	V <sub>EB</sub> = -0.5V, f = 1MHz,
Output Capacitance	C <sub>obo</sub>		23.5	40	pF	V <sub>CB</sub> = -10V, f = 1MHz,
Delay Time	t <sub>d</sub>	_	24.7	_	ns	
Rise Time	t <sub>r</sub>	_	22.4	_	ns	$I_C = -500 \text{mA}, V_{CC} = -10 \text{V},$ $I_{B1} = -I_{B2} = -50 \text{mA}$
Storage Time	ts		660	_	ns	$R_{b} = -182 = -50 \text{ mA}$ $R_{b} = 100 \Omega, R_{c} = 20 \Omega$
Fall Time	$t_f$	1	107	_	ns	10032,110 2032

Note: 12. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.



### Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

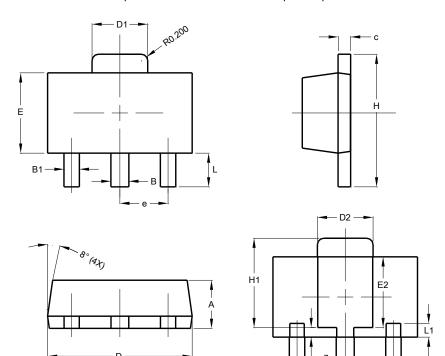






## **Package Outline Dimensions**

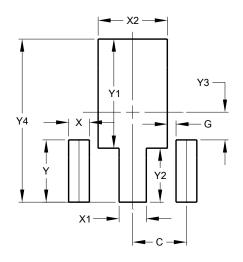
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT89					
Dim	Min	Max	Тур		
Α	1.40	1.60	1.50		
В	0.50	0.62	0.56		
B1	0.42	0.54	0.48		
С	0.35	0.43	0.38		
D	4.40	4.60	4.50		
D1	1.62	1.83	1.733		
D2	1.61	1.81	1.71		
Е	2.40	2.60	2.50		
E2	2.05	2.35	2.20		
е	_	-	1.50		
Н	3.95	4.25	4.10		
H1	2.63	2.93	2.78		
L	0.90	1.20	1.05		
L1	0.327	0.527	0.427		
Z	0.20	0.40	0.30		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	1.500
G	0.244
Х	0.580
X1	0.760
X2	1.933
Υ	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.





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